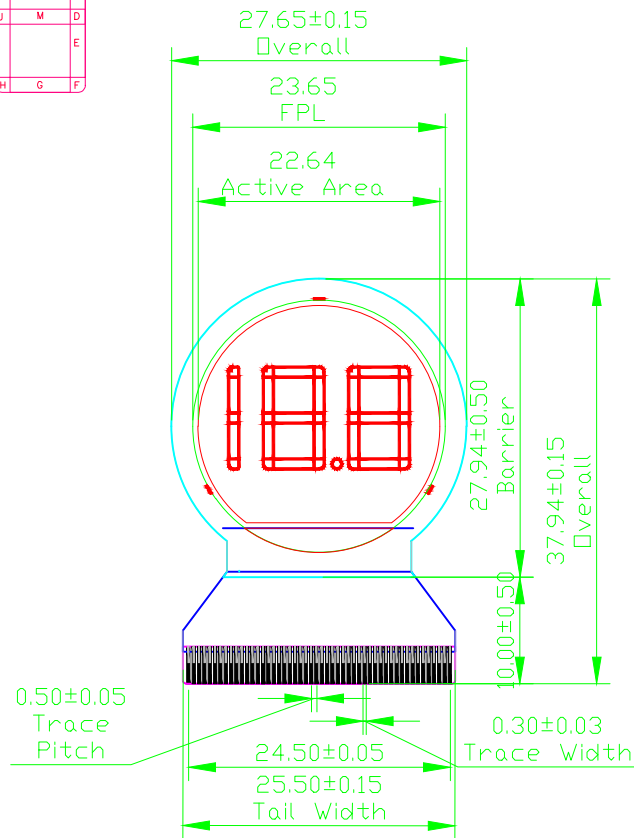
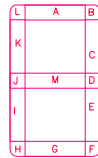


33seg round PIN_MAP		
PIN MAP		
PIN	Description	segment
1	Top electrode	
2	Field	1
3	A A	2
4	A B	3
5	A C	4
6	A D	5
7	A E	6
8	A F	7
9	A G	8
10	A H	9
11	A I	10
12	DP	11
13	A J	12
14	B F	13
15	A K	14
16	A L	15
17	A M	16
18	B E	17
19	B D	18
20	B C	19
21	B G	20
22	B H	21
23	B B	22
24	B I	23
25	B J	24
26	B K	25
27	B L	26
28	C H	27
29	C I	28
30	C J	29
31	C K	30
32	C L	31
33	B A	32
34	B M	33

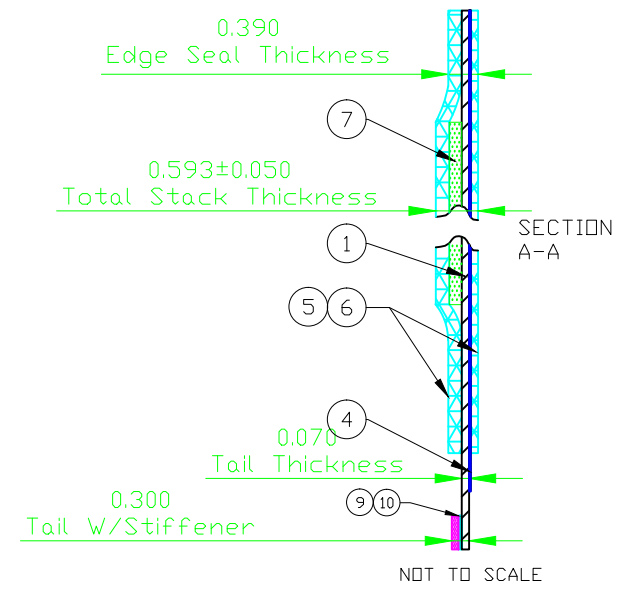


25-50  
blank  
Connector-  
Tyco  
5-1734592-0

REV.	DESCRIPTION	DESIGN	DATE
	INITIAL RELEASE		

SDC 2 (100UM THICK PTF BACKPLANE) MATERIALS LIST				
ITEM	LAYER COLOR	DESCRIPTION	MATERIAL	THICKNESS (µm)
1		BACKPLANE	MYLAR PET	100
2		ELECTRODE-FRONT	CARBON	12.50
3		ELECTRODE-REAR 1	SILVER	12.50
4		ELECTRODE-REAR 2	CARBON	12.50
5		DIELECTRIC	DIELECTRIC	35
6		FRONT BARRIER	EINK 110-1031	175
7		REAR BARRIER	EINK 110-1032	100
8		FPL	340-1934 (220S)	175
9		STIFFENER	MYLAR PET	180
10		STIFFENER ADHESIVE	PSA	50

Note:  
1. SDC should be built in accordance with the MFG Spec.  
2. Critical Dimensions Should Be Denoted with Min-Max Tolerances.



MATERIAL	HEAT & SURFACE TREATMENT	E Ink Holdings Inc.		
APPROVE	S ONEIL	SCALE	UNIT	PROJECTION METHOD
CHECK	S ONEIL	1/1	mm	33 seg round
DESIGN	S ONEIL	ORIGINAL NAME	DWG. NO.	REV. SHEET
			SS009221	03 1/1